

Features and Benefits

- 9.0W/m-K thermal conductivity
- Excellent thermal conductivity
- Never dries
- RoHS compliant
- Halogen-free

OU-809P is a high Compressible Gap Filler (Putty Type) with high performance thermally conductive compound and will not dry out. The surface consistency is excellent for filling surface irregularities as OU-809P is Sheet structure, which is convenient to use.

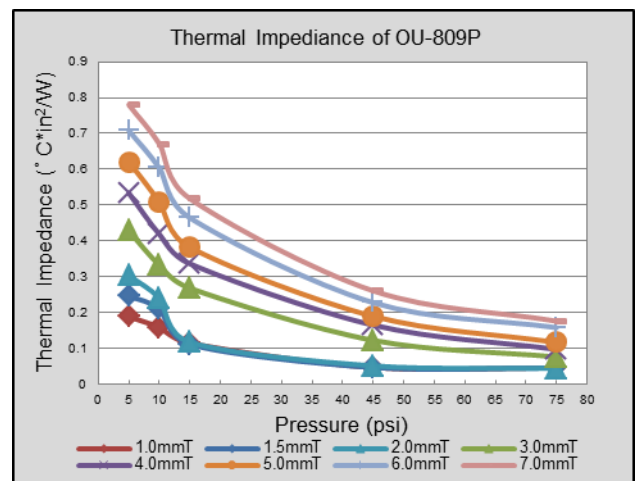
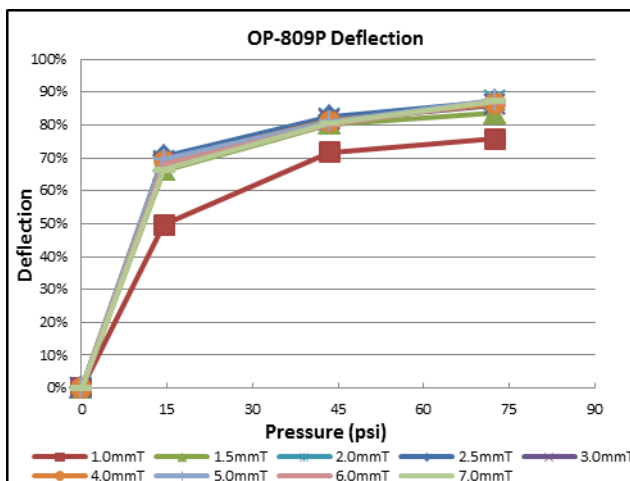
OU-809P provides a cost effective solution for application where rapid heat transfer from heat source to spreader is required. OU-809P is RoHS compliant and halogen-free, offering extra reassurance in applications which hazardous substances are forbidden.

Typical Applications

- Heat source to spreader/sink in computer and peripherals
- Power conversion equipments
- Cooling components to the chassis, frame or other types of heat spreader
- Wireless communication hardware
- Automotive control units
- Power supply
- Audio and video component
- Micro processor

Typical Properties	OU-809P	Test Method
Construction & Composition	Silicone-based putty	—
Color	Gray	Visual
Thickness Range /inch (mm)	0.04"~0.40" (1.0~10.16) in 0.01" (0.254) increments	—
Standard Sheet Size(mm)	200 * 400	—
Density (g.cm ⁻³)	3.4	—
Thermal Conductivity (W.m ⁻¹ .K ⁻¹)	9	ASTM D5470 (modified)
Breakdown Voltage(KV/mm)	10	ASTM D149
Dielectric Strength (KVac/mm)	N/A	ASTM D149
Temperature Range (°C)	-40~180°C	—
UL Flammability Rating	UL94 V0	—
Shelf Life /Months	24	—

Please contact us for other special requirements



Hong Kong
Tel: (852) 2686 8168
Fax: (852) 2686 8268
E-mail: emeihk@emeigroup.com

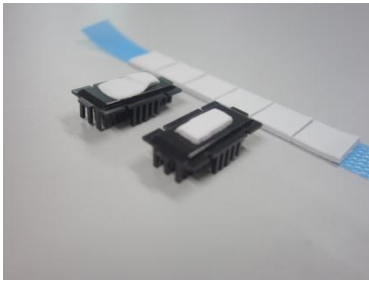
Dongguan
Tel: (86) 769-8334 1628
Tel: (86) 769-8334 2028
E-mail: emeidg@emeigroup.com

Shanghai
Tel: (86) 21-5868 3381
Tel: (86) 21-5868 3386
E-mail: emeish@emeigroup.com

Taiwan
Tel: (886) 2-2793 9055
Tel: (886) 2-2793 9501
E-mail: emeitw@emeigroup.com

www.emeigroup.com

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产品特点

- 导热率 9.0W/m-K
- 出众的导热性能
- 电绝缘
- 符合 RoHS 规格
- 无卤素

OU-809P 是一种拥有高压缩性和高导热效能的导热填充垫，永不干涸。这款导热填充垫能够在低应用压力的情况下保持不规则表面间的良好接触，OU-809P 是片状，方便使用。

OU-809P 为需要从热源到散热器的快速热传递的应用提供成本有效的解决方案。

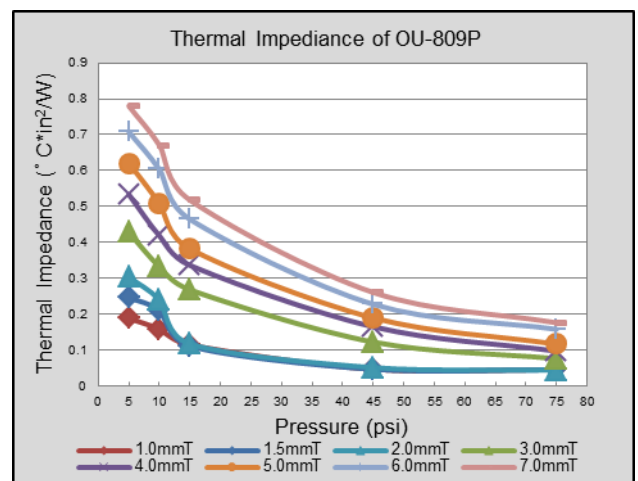
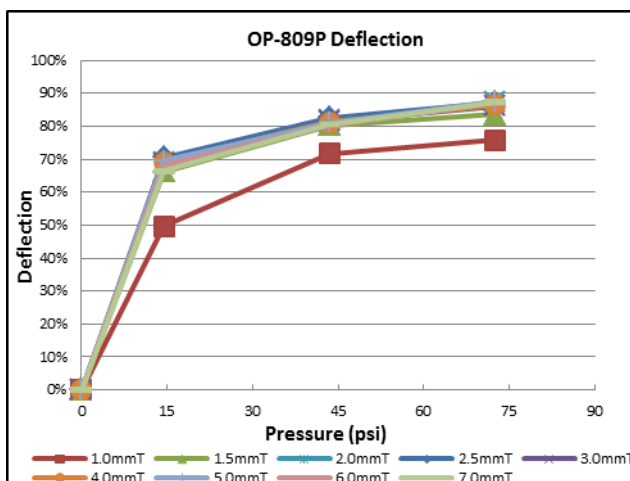
独有的产品配方不单指符合 RoHS 规格更达到无卤素要求，令客户在使用时对于有害物质的控制更有信心。

一般应用

- 计算机散热组件
- 电源转换设备
- 底盘，框架或其他散热组件
- 通信用硬件
- 自动化组件
- 电源供应设备
- 音频和视频组件
- 微处理器

一般特性	OU-809P	测试方法
结构及主要成分	硅树脂复合物	—
颜色	灰色	目测
厚度 / inch (mm)	0.04"~0.40" (1.0~10.16) in 0.01" (0.254) increments	—
标准片材尺寸(mm)	200 * 400	—
密度 (g.cm ⁻³)	3.4	—
导热率(W.m ⁻¹ .K ⁻¹)	9	ASTM D5470 (modified)
击穿电压(KV/mm)	10	ASTM D149
介电强度(KVac/mm)	N/A	ASTM D149
使用温度 (°C)	-40~180°C	—
UL 燃烧等级	UL94 V0	—
有效期(Months)	24	—

如对产品有其它特殊要求，请联系我们



Tel: (852) 2686 8168
Fax: (852) 2686 8268
E-mail: emeihk@emeigroup.com

东莞
(86) 769-8334 1628
(86) 769-8334 2028
emeidg@emeigroup.com

上海
(86) 21-5868 3381
(86) 21-5868 3386
emeish@emeigroup.com

台湾
(886) 2-2793 9055
(886) 2-2793 9501
emeitw@emeigroup.com

www.emeigroup.com

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